Fabrication of flexible electrically conductive polymer based micro-patterns using plasma discharge

Asma Abdulkareem^{1,2}, Anton Popelka², Jolly Bhadra², Se won Jang², NooraAl-Thani²



¹Department of Materials Science & Technology, Qatar University, P.O. Box 2713, Doha, Qatar

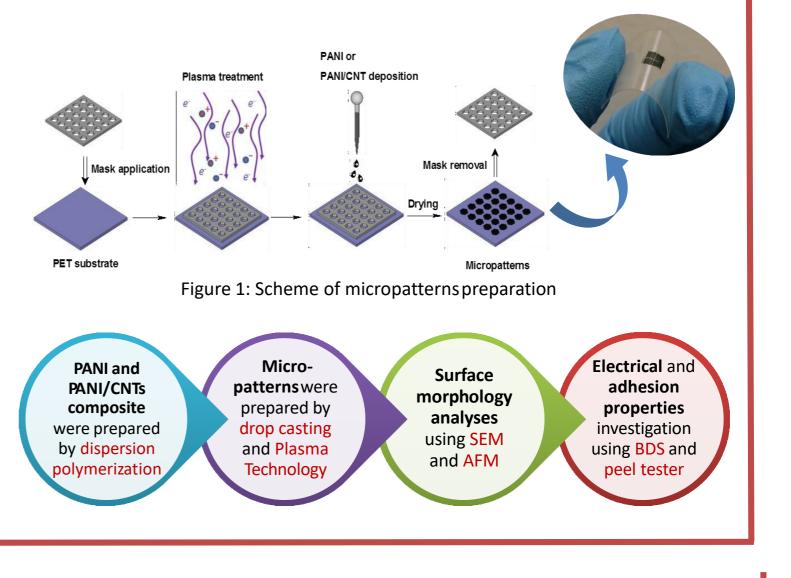
²Center for Advanced Materials, Qatar University, P.O. Box 2713, Doha, Qatar

Graduate student, **Energy, Environment & Resource** Sustainability.

Email: asma.alkreem@qu.edu.qa

1. Abstract

Since past few decades a simple, high efficient and economical method for fabrication of high conducting micro-patterns for the application in the field of **flexible micro-electronics** has become the focus of interest. A number of novel approaches are implemented to reach the goal, such as nano imprinting [1, 2], micro contact printing [3], dip-pen lithography [4]. In all these techniques, flexible patterns were made up of **polymeric materials** using small quantity of conducting fillers, resulting into limited or low conductivity. A **conductive polymer** represents material, which can be effective used for replacement of traditional materials used in electronics applications, such as metals, because of their excellent flexible and chemical inertness properties and low cost. This work aimed to enhance the **electrical conductivity** of prepared **micro-patterns** by using silicon mask and drop casting method in combination with plasma treatment.



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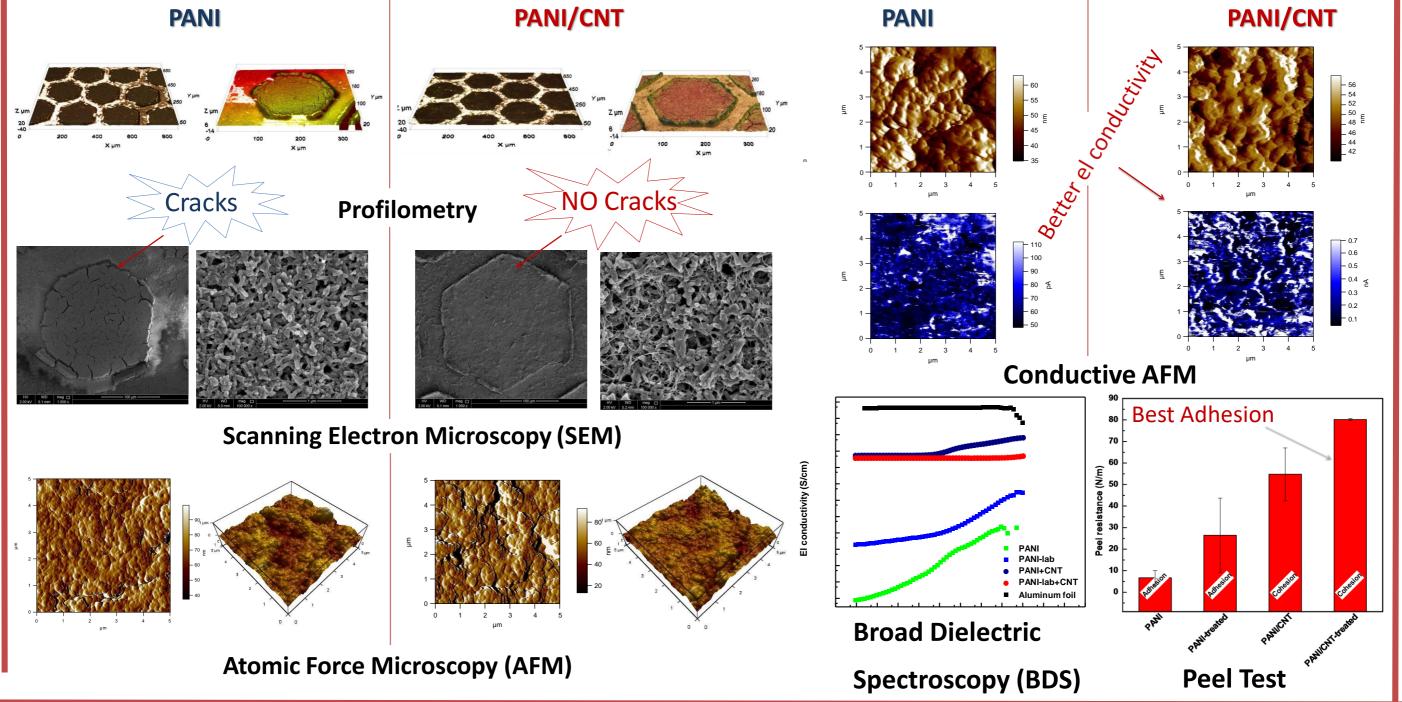
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3.Results and Discussion **3.1 SURFACE MORPHOLOGY**

PANI/CNT PANI

3.2 ELECTRICAL CONDUCTIVITY & ADHESION





2. Methodology

4.Conclusion

- The PANI and PANI-CNT micro-patterns were fabricated on the PET (flexible substrate) using low-temperature plasma as **adhesion promoter** confirmed by peel test.
- Different microscopic techniques (Profilometry, SEM, AFM) proved the homogeneous structures of micro-patterns.
- BDS and Conductive AFM confirmed electrical behavior of prepared micro-patterns, especially using **PANI-CNT**.

5. References

[1]T. Mäkelä et al., Microelectronic Engineering, 84 (2007) 877. [2] M. Schulz et al., Elsevier Science (2013) 87. [3]S. Rodríguez et al., Journal of Chromatography, A 1357 (2014) 110. [4]C. X. Liu et al., Nanomaterials, 2 (2012) 329.

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